LX7176A

User Guide
LX7176A 4 Amp Step-Down Converter Evaluation Board





Contents

1	Revision 1.0	1
	Product Description	
	2.1 Applications	
	2.2 Key Features	2
3	Evaluation Board Schematic	3
	Recommended Operating Conditions	
5	PCB Layout of Evaluation Board	5
6	LX7176A_Bill of Materials	9
7	Dynamic Load Response Scope Shots	10
8	Start-up and Short Condition Scope Shots	13
9	Ordering Information	15



1 Revision 1.0

Revision 1.0 was published in August 2017 and was the first publication of this document.



2 Product Description

The LX7176A is a 4 A step-down regulator with integrated MOSFETs packaged in a space saving QFN12 2 mm \times 2 mm for today's mobile devices. It uses an ultra fast, constant frequency hysteretic control method to minimize external filter components while maintaining excellent regulation. The LX7176A reference voltage is 0.6 V.

The LX7176A operates from 3 V to 5.5 V rails and outputs 0.6 V to 100% of the input voltage.

Cycle-by-cycle current limiting protects against over-current conditions. Hiccup mode provides protection for heavy over-load or short-circuit faults. Thermal protection shuts down the regulator under over-temperature conditions. Over voltage conditions will immediately shut off the output to protect against permanent damage. The LX7176A automatically restarts when all fault conditions are cleared. Internal soft start circuitry limits start up inrush currents.

2.1 Applications

- High-performance HDDs
- LCD TVs
- Notebooks/Netbooks
- Servers and workstations
- Video cards
- PoE-powered devices
- Smart phones

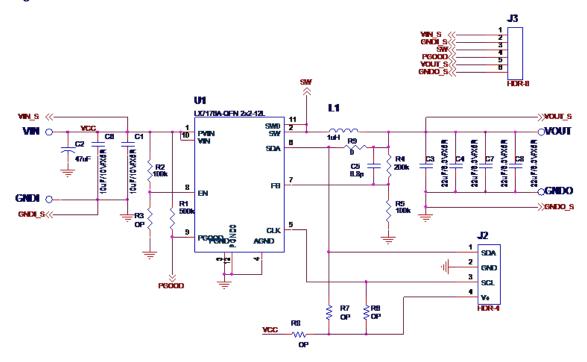
2.2 Key Features

- 0 A–4 A step-down regulator
- Operational input supply voltage range: 3 V–5.5 V (short durations to 6.5 V)
- Hysteretic control offers best transient response
- CCM switching at a constant 1.65 MHz
- Automatically switches to DCM switching under light loads to improve efficiency
- 100% duty ratio operation
- Input under voltage and over voltage protection
- Enable and Power Good Function
- Internal soft-start
- Cycle-by-cycle over current protection
- Hiccup mode protects against short circuit faults
- RoHS-compliant



3 Evaluation Board Schematic

Figure 1 • Schematic of Evaluation Board





4 Recommended Operating Conditions

Table 1 • Operating Conditions

Description	Symbol	Minimum	Maximum	Unit
Input voltage	Vin	3.0	5.5	V
Output voltage	Vоит	0.6	5.5	V
Output current (V _{IN} = 3 V to 5 V)	Іоит	0	4	Α
Operating ambient temperature	TA	0	85	°C
Enable chip	EN	Vin		
Shut down chip	EN		Pull to GND	

4.1 Setting the Output Voltage

In case a higher output voltage is needed, it must be programmed through an external resistor divider connected from SW to VOUT then to GND. The formula below calculates the value of VOUT based on the resistor divider R1 and R2.

$$VOUT = V_{REF} \times \left(1 + \frac{R1}{R2}\right)$$

 V_{REF} is determined by the chip, for example, to set the LX7176A to a V_{OUT} = 1.8 V, given V_{REF} = 0.6 V. First pick the lower resistor R_2 = 100k, calculate the upper resistor R_1 = 200k.



5 PCB Layout of Evaluation Board

The LX7176A EVAL Board is a four-layer board. The recommended distance between ground layer and the top layer is 6mil.

The following illustrations show the four layers of the LX7176A board.

Figure 2 • Layer 1: Top Layer

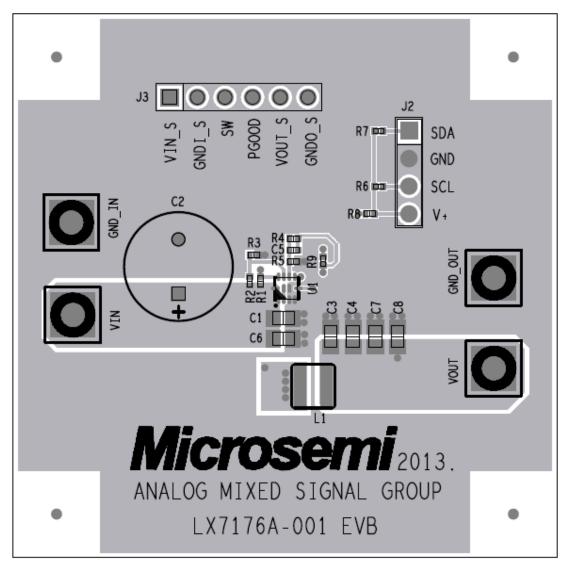




Figure 3 • Layer 2: Ground Layer

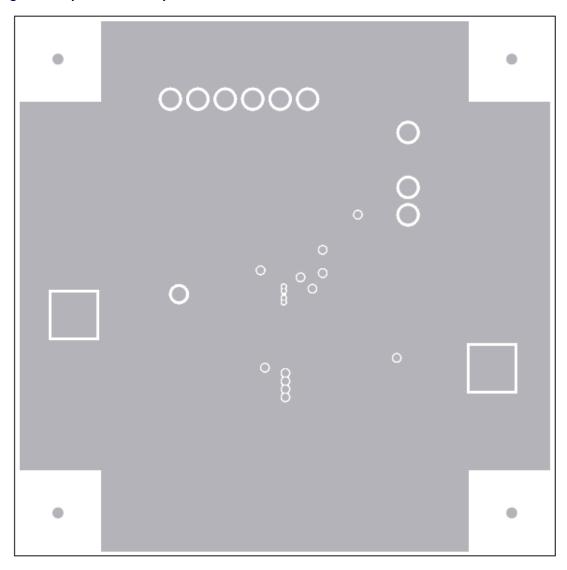




Figure 4 • Layer 3: Sense Layer

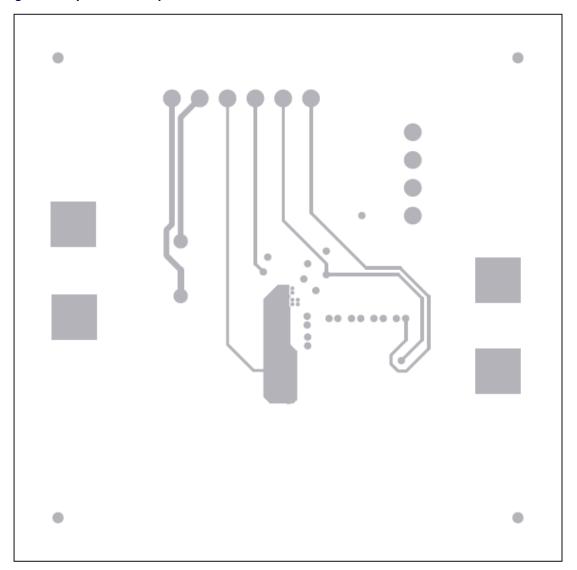
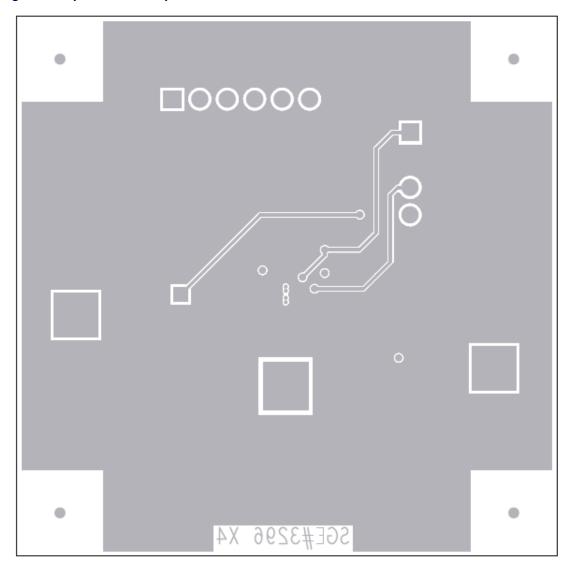




Figure 5 • Layer 4: Bottom Layer





6 LX7176A_Bill of Materials

The following table lists the bill of materials (BOM) for the LX7176A Evaluation Board.

Table 2 • BOM

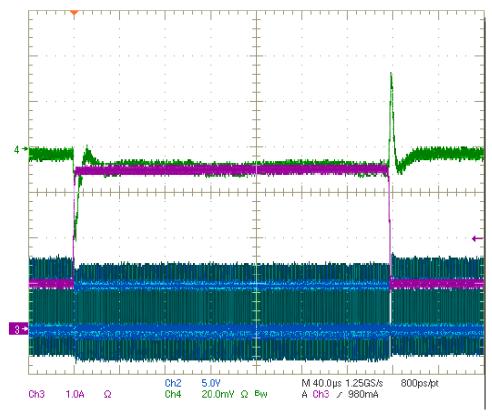
1 Microsemi IC – LX7176A U1 2 Test Point (J3) SW, PGOOD, VIN_S, VO 3 Terminal VIN, VOUT, GND, GND 4 Jumper/4pin J2 5 10 μF/10 V/10%/0805/X5R C1, C6 6 47 μF Electronic/35 V C2 7 22 μF/6.3 V/10%/0805/X5R C3 8 500 kΩ/1%/0402 R1	1 _S, GND_S, GND_S 6 4 1
3 Terminal VIN, VOUT, GND, GND 4 Jumper/4pin J2 5 10 μF/10 V/10%/0805/X5R C1, C6 6 47 μF Electronic/35 V C2 7 22 μF/6.3 V/10%/0805/X5R C3	4
4 Jumper/4pin J2 5 10 μF/10 V/10%/0805/X5R C1, C6 6 47 μF Electronic/35 V C2 7 22 μF/6.3 V/10%/0805/X5R C3	
5 10 μF/10 V/10%/0805/X5R C1, C6 6 47 μF Electronic/35 V C2 7 22 μF/6.3 V/10%/0805/X5R C3	1
6 47 μF Electronic/35 V C2 7 22 μF/6.3 V/10%/0805/X5R C3	
7 22 μF/6.3 V/10%/0805/X5R C3	2
	1
8 500 kΩ/1%/0402 R1	4
	1
9 100 kΩ/1%/0402 R2	1
10 200 kΩ/1%/0402 R4	1
11 100 kΩ/1%/0402 R5	1
12 0 Ω/1%/0402 R9	1
13 1 μH – XAL4020-102ME L1	



7 Dynamic Load Response Scope Shots

(Load Current = 1 A to 3.5 A, L = 1 μ H, Cout = 88 μ F)

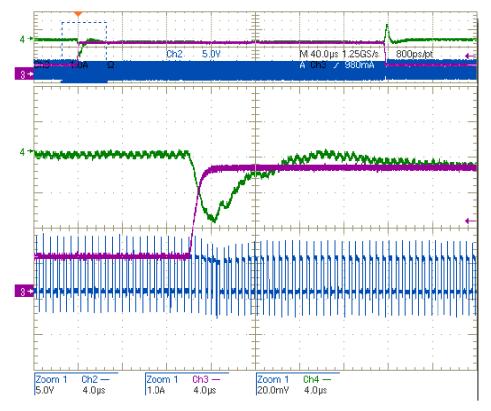
Figure 6 • Step Response



CH2: SW Node, CH3: ILOAD, CH4: VOUT AC.



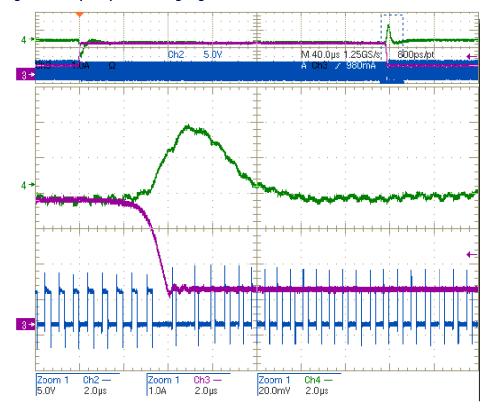
Figure 7 • Step Response Rising Edge



CH2: SW Node, CH3: ILOAD, CH4: VOUT AC.



Figure 8 • Step Response Falling Edge

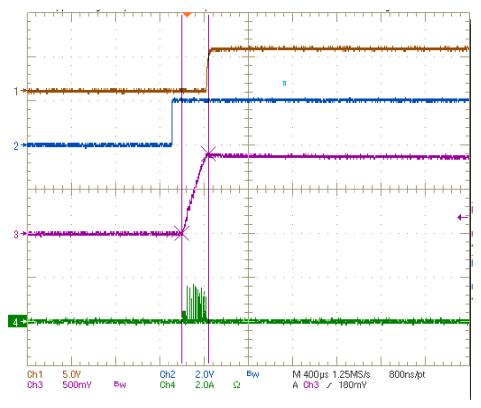


CH2: SW Node, CH3: ILOAD, CH4: VOUT AC.



8 Start-up and Short Condition Scope Shots

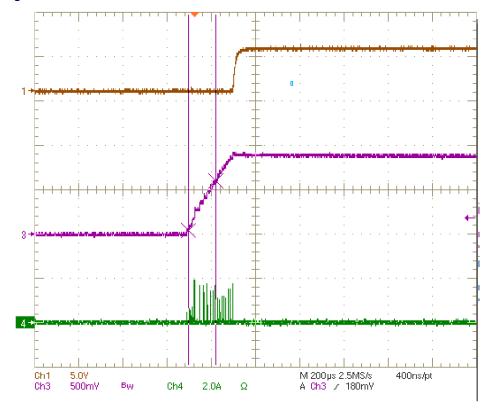
Figure 9 • Start-up with ENABLE Toggled



CH1: PG, CH2: EN, CH3: Vout, CH4: inductor current.



Figure 10 • Soft-Start VIN Tied to ENABLE



CH1: PG, CH3: Vouт, CH4: inductor current.



9 Ordering Information

Table 3 • Ordering Information

Part Order Number	Description
LX7176ACLQ	QFN 2x2mm 12-layer integrated circuit
LX7176A EVAL BOARD	Evaluation PCB for LX7176A





Microsemi Corporate Headquarters

One Enterprise, Aliso Viejo, CA 92656 USA Within the USA: +1 (800) 713-4113 Outside the USA: +1 (949) 380-6100 Fax: +1 (949) 215-4996 Email: sales.support@microsemi.com www.microsemi.com

© 2017 Microsemi Corporation. All rights reserved. Microsemi and the Microsemi logo are trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or prameters provided by Microsemi. It is the Buyer's responsibility to independently determine suitability of any products and to test and verify the same. The information provided by Microsemi hereunder is provided is, where is' and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information itself or anything described by such information. Information provided in this document is proprietary to Microsemi, and Microsemi reserves the right to make any changes to the information in this document or to any products and services at any time without notice.

Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions; security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, California, and has approximately 4,800 employees globally. Learn more at www.microsemi.com.

MSCC-0102-UG-01004-1.0-0717